

RoHS

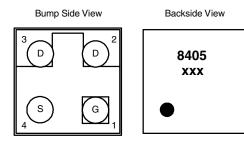
COMPLIANT

**Vishay Siliconix** 

# 12 V P-Channel 1.8 V (G-S) MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	<b>R<sub>DS(on)</sub> (</b> Ω <b>)</b>	I <sub>D</sub> (A)		
	0.055 at V <sub>GS</sub> = - 4.5 V	- 4.9		
- 12	0.070 at V <sub>GS</sub> = - 2.5 V	- 4.4		
	0.090 at V <sub>GS</sub> = - 1.8 V	- 4		

#### **MICRO FOOT**



Device Marking: 8405 xxx = Date/Lot Traceability Code

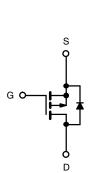
Ordering Information: Si8405DB-T1-E1 (Lead (Pb)-free and Halogen-free)

### FEATURES

- TrenchFET<sup>®</sup> Power MOSFET
- MICRO FOOT<sup>®</sup> Chipscale Packaging Reduces Footprint Area Profile (0.62 mm) and On-Resistance Per Footprint Area
- Material categorization:
  For definitions of compliance please see <u>www.vishay.com/doc?99912</u>

### **APPLICATIONS**

- PA, Battery and Load Switch
- Battery Charger Switch



P-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> ( $T_A = 25 \text{ °C}$ , unless otherwise noted)							
Parameter		Symbol	5 s	Steady State	Unit		
Drain-Source Voltage		V <sub>DS</sub>	- 12		V		
Gate-Source Voltage		V <sub>GS</sub>	± 8				
Continuous Drain Current /T 150 °C\8	T <sub>A</sub> = 25 °C	I <sub>D</sub> - 4.9 - 3.9	- 4.9	- 3.6			
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 70 °C		- 3.9	- 2.8	•		
Pulsed Drain Current		I <sub>DM</sub>	- 10		A		
Continuous Source Current (Diode Conduction) <sup>a</sup>		۱ <sub>S</sub>	- 2.5	- 1.3			
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C	P <sub>D</sub>	1.47	W			
	T <sub>A</sub> = 70 °C		1.77	0.94	vv		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150		°C		
Package Reflow Conditions <sup>b</sup>	IR/Convection		260				

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
	t ≤ 5 s	R <sub>thJA</sub>	35	45	
Maximum Junction-to-Ambient <sup>a</sup>	Steady State	' 'thJA	72	85	°C/W
Maximum Junction-to-Foot (drain)	Steady State	R <sub>thJF</sub>	16	20	

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. Refer to IPC/JEDEC (J-STD-020), no manual or hand soldering.

c. In this document, any reference to case represents the body of the MICRO FOOT device and foot is the bump.

# Si8405DB

## Vishay Siliconix



Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
Static							
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 0.45	- 0.7	- 0.95	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 8 V$			± 100	nA	
Zero Gate Voltage Drain Current		V <sub>DS</sub> = - 12 V, V <sub>GS</sub> = 0 V			- 1		
	IDSS	$V_{DS}$ = - 12 V, $V_{GS}$ = 0 V, $T_{J}$ = 70 °C			- 5	μΑ	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le$ - 5 V, $V_{GS}$ = - 4.5 V	- 5			А	
Drain-Source On-State Resistance <sup>a</sup>		$V_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -1 \text{ A}$		0.045	0.055		
	R <sub>DS(on)</sub>	$V_{GS} = -2.5 \text{ V}, \text{ I}_{D} = -1 \text{ A}$		0.055	0.070	Ω	
		$V_{GS} = -1.8 \text{ V}, I_D = -1 \text{ A}$		0.073	0.090		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 10 V, I <sub>D</sub> = - 1 A		6		S	
Diode Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>S</sub> = - 1 A, V <sub>GS</sub> = 0 V		- 0.73	- 1.1	V	
Dynamic <sup>b</sup>	•		•	•			
Total Gate Charge	Qg			14	21		
Gate-Source Charge	Q <sub>gs</sub>	$Q_{gs}$ V <sub>DS</sub> = -6 V, V <sub>GS</sub> = -4.5 V, I <sub>D</sub> = -1 A		1.7		nC	
Gate-Drain Charge	Q <sub>gd</sub>			2.5		1	
Turn-On Delay Time	t <sub>d(on)</sub>			16	25		
Rise Time	t <sub>r</sub>	$V_{DD}$ = - 6 V, $R_L$ = 6 $\Omega$		32	50		
Turn-Off Delay Time	t <sub>d(off)</sub>	$\text{I}_\text{D}\cong$ - 1 A, $\text{V}_\text{GEN}$ = - 4.5 V, $\text{R}_\text{g}$ = 6 $\Omega$		120	180	ns	
Fall Time	t <sub>f</sub>			80	120		
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = - 1 A, dl/dt = 100 A/μs		46	70		

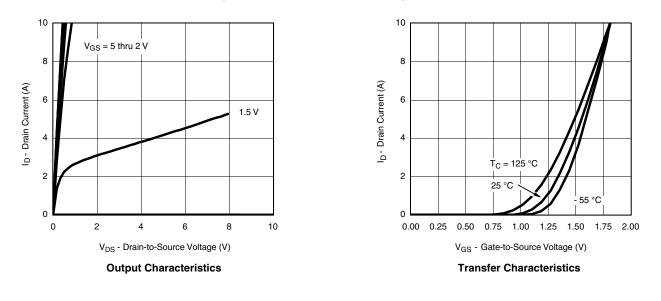
Notes:

a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



www.vishay.com 2 For technical questions, contact: pmostechsupport@vishay.com

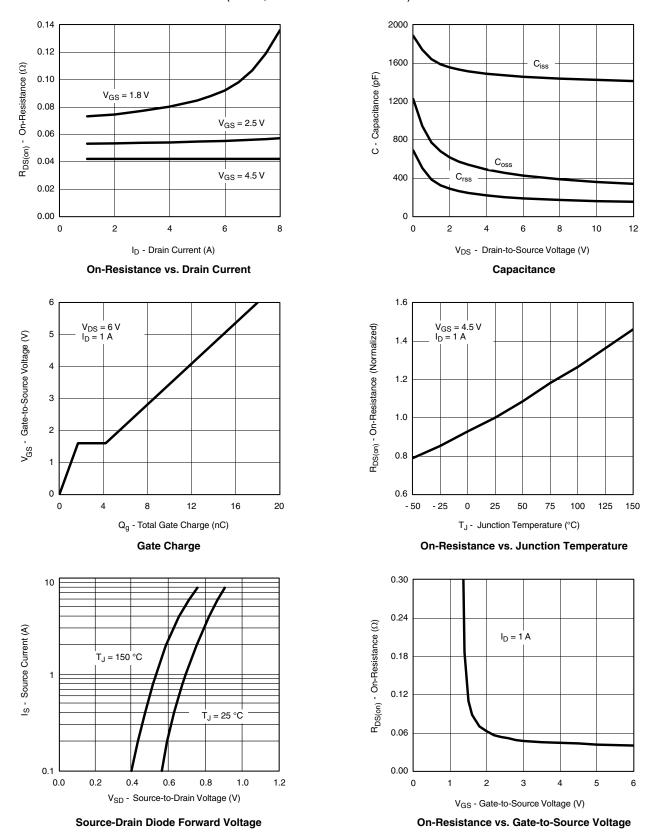
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## Si8405DB Vishay Siliconix

### **TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



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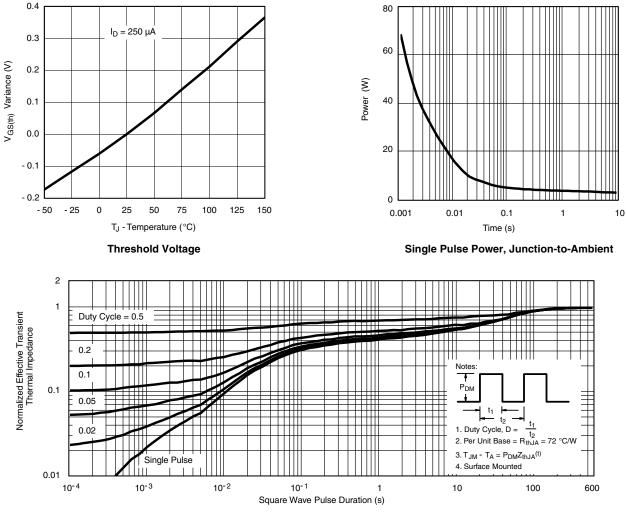
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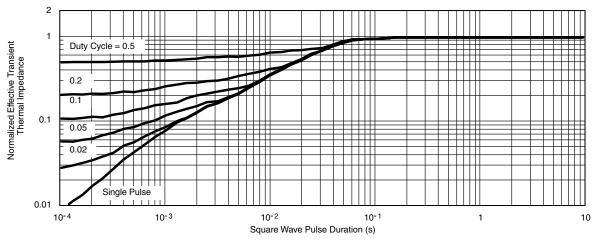
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### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient





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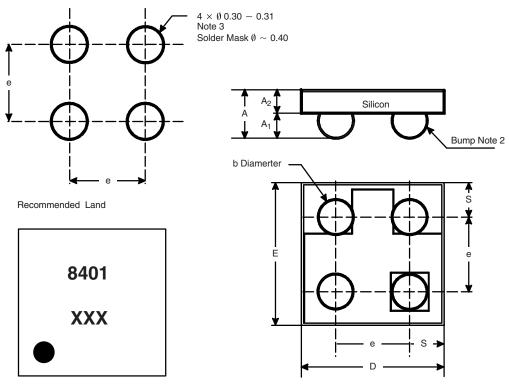
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### **PACKAGE OUTLINE**

### MICRO FOOT: 4-BUMP (0.8 mm PITCH)



Mark on Backside of Die

Notes (unless otherwise specified):

1. Laser mark on the silicon die back, coated with a thin metal.

2. Bumps are 95.5/3.8/0.7 Sn/Ag/Cu.

- 3. Non-solder mask defined copper landing pad.
- 4. The flat side of wafers is oriented at the bottom.

Dim.	Millim	eters <sup>a</sup>	Inch	nes
	Min.	Max.	Min.	Max.
Α	0.600	0.650	0.0236	0.0256
A <sub>1</sub>	0.260	0.290	0.0102	0.0114
A <sub>2</sub>	0.340	0.360	0.0134	0.0142
b	0.370	0.410	0.0146	0.0161
D	1.520	1.600	0.0598	0.0630
E	1.520	1.600	0.0598	0.0630
е	0.800		0.03	15
S	0.360	0.400	0.0142	0.0157

Notes:

a. Use millimeters as the primary measurement.

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